

- ★ Super Low Gate Charge
- ★ 100% EAS Guaranteed
- ★ Green Device Available
- ★ Excellent CdV/dt effect decline
- ★ Advanced high cell density Trench technology

Product Summary



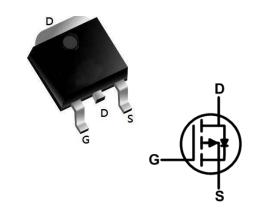
BVDSS	RDSON	ID
-100V	59mΩ	-25A

Description

The XR25P10Áis the high cell density trenched P-ch MOSFETs, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

The XR25P10 meet the RoHS and Green Product requirement 100% EAS guaranteed with full function reliability approved.

TO252-3L Pin Configuration



Absolute Maximum Ratings (T_A = 25°C, unless otherwise noted)

Parameter	Symbol	Value	Unit		
Drain-Source Voltage		V _{DS}	-100	V	
Gate-Source Voltage	V _{GS}	±20	V		
	T _C = 25°C		-25	А	
Continuous Drain Current	T _C = 100°C	- I _D	-11		
Pulsed Drain Current ¹	Ірм	-72	А		
Single Pulse Avalanche Energy ²		EAS	42	mJ	
Total Power Dissipation Tc= 25°C		P _D	102	W	
Operating Junction and Storage Temper	Тл, Тата	-55 to 150	°C		

Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance from Junction-to-Ambient ³	Reja	91	°C/W
Thermal Resistance from Junction-to-Case	Rejc	1.22	°C/W



Electrical Characteristics (T_J = 25°C, unless otherwise noted)

Parameter		Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static Characteristics				•				
Drain-Source Breakdown Voltage		V _{(BR)DSS}	V _{GS} = 0V, I _D = -250μA	-100	-	-	V	
Gate-body Leakage curren	t	I _{GSS}	V _{DS} = 0V, V _{GS} = ±20V	-	-	±100	nA	
Zero Gate Voltage Drain	T _J = 25°C		\\ - 400\\ \\ - 0\\	-	-	-1	μА	
Current	T _J = 100°C	IDSS	V _{DS} = -100V, V _{GS} = 0V	-	-	-20		
Gate-Threshold Voltage		V _{GS(th)}	V _{DS} = V _{GS} , I _D = -250μA	-1.5	-2	-2.5	V	
Drain-Source On-Resistan	204	D	V _{GS} = -10V, I _D = -10A	-	59	70		
Drain-Source On-Resistan	se ·	R _{DS(on)}	V _{GS} = -4.5V, I _D = -6A	V _{GS} = -4.5V, I _D = -6A 120		150	- mΩ	
Forward Transconductance	e ⁴	G fs	V _{DS} = -10V, I _D = -10A	-	28	-	S	
Dynamic Characteristi	CS ⁵							
Input Capacitance		C _{iss}		-	2859	-	pF	
Output Capacitance		Coss	$V_{DS} = -50V, V_{GS} = 0V,$ f = 1MHz	-	93	-		
Reverse Transfer Capacita	nce	C _{rss}		-	68	-		
Gate Resistance		Rg	f = 1MHz	-	4.3	-	Ω	
Switching Characterist	ics ⁵							
Total Gate Charge		\mathbf{Q}_{g}		-	53	-	nC	
Gate-Source Charge		Qgs	$V_{GS} = -10V, V_{DS} = -50V,$ $I_{D} = -10A$	-	12	-		
Gate-Drain Charge		\mathbf{Q}_{gd}	- -	-	10	-		
Turn-On Delay Time		t _{d(on)}		-	8	-		
Rise Time		t r	$V_{GS} = -10V, V_{DD} = -50V,$	-	27	-	ns	
Turn-Off Delay Time		t _{d(off)}	$R_G = 3\Omega$, $I_D = -10A$	-	155	-		
Fall Time		t f	-	-	77	-		
Body Diode Reverse Recovery Time		t _{rr}	1 404 41/44 4004/	-	36	-	ns	
Body Diode Reverse Recovery Charge		Qrr	- I _F = -10A,dI/dt= 100A/μs	-	40	-	nC	
Drain-Source Body Did	de Characte	eristics						
Diode Forward Voltage ⁴		V _{SD}	I _S = -10A, V _{GS} = 0V	-	-0.9	-1.3	V	
Continuous Source Curren	t T _C = 25°C	Is	-	-	-	25	Α	

Notes:

- 1. Repetitive rating, pulse width limited by junction temperature $T_{J(MAX)}$ =150°C.
- 2. The EAS data shows Max. rating . The test condition is V_{DD} = -35V, V_{GS} = -10V, L= 0.5mH, I_{AS} = -23A
- 3. The data tested by surface mounted on a 1 inch2 FR-4 board with 2OZ copper, The value in any given application depends on the user's specific board design.
- 4. The data tested by pulsed , pulse width $\leq 300 us$, duty cycle $\leq 2\%.$
- 5. This value is guaranteed by design hence it is not included in the production test..



Typical Performance Characteristics

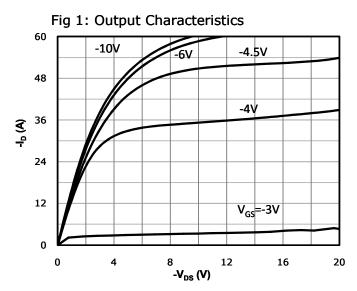
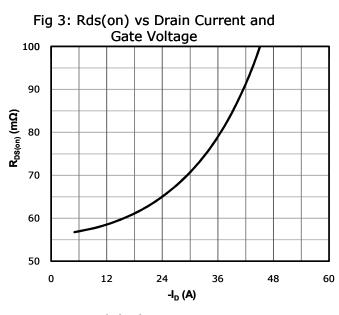
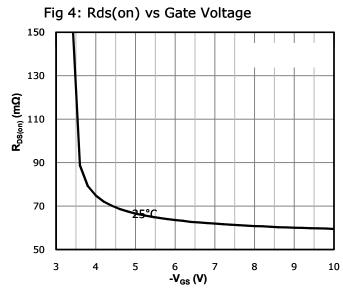
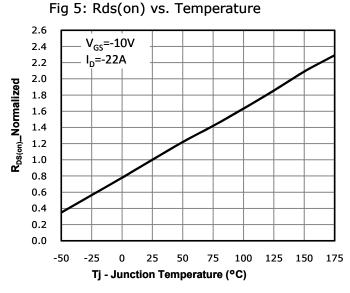


Fig 2: Transfer Characteristics 50 $V_{DS} = -5V$ 40 30 € 20 150°C 10 25°C 0 2 5 6 1 3 $-V_{GS}(V)$







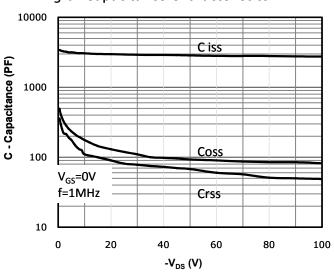


Fig 6: Capacitance Characteristics



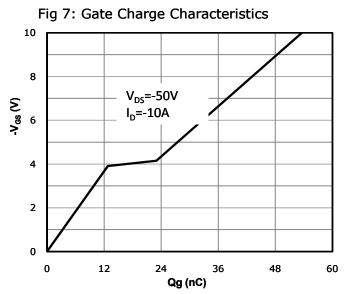


Fig 8: Body-diode Forward
Characteristics

1000

100

150°C

150°

Fig 9: Power Dissipation

120
100
80
40
20
0 25 50 75 100 125 150
Tc - Case Temperature (°C)

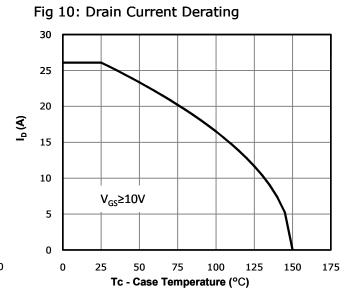


Fig 11: Safe Operating Area

1000

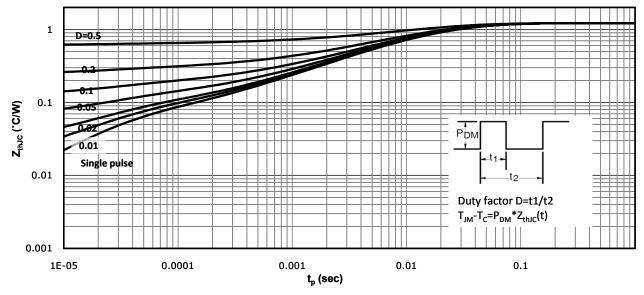
Limited by Rds(on)

100 Rds(on)

10



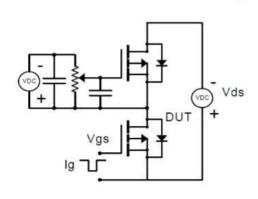
Fig 12: Max. Transient Thermal Impedance

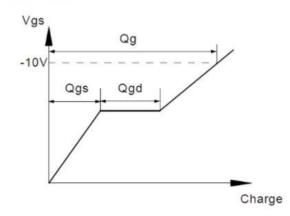




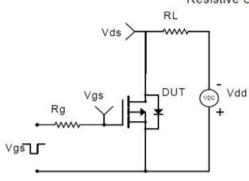
Test Circuit & Waveform

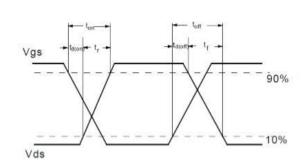
Gate Charge Test Circuit & Waveform



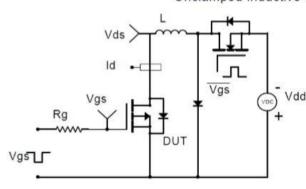


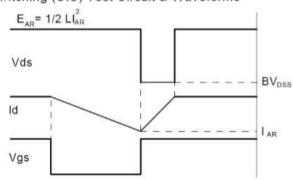
Resistive Switching Test Circuit & Waveforms



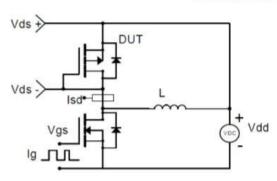


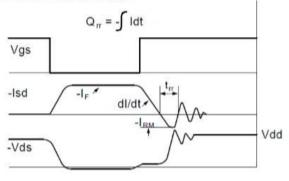
Unclamped Inductive Switching (UIS) Test Circuit & Waveforms





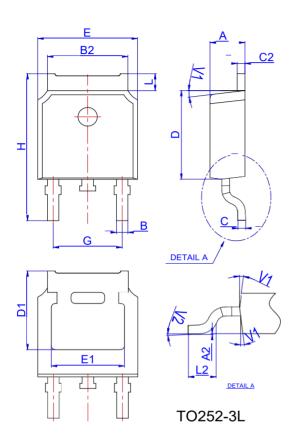
Diode Recovery Test Circuit & Waveforms





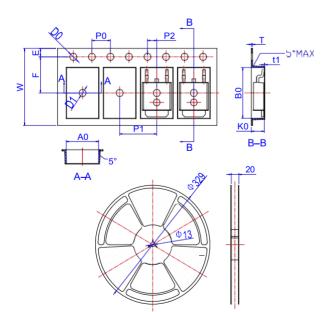


Package Mechanical Data-TO252-3L



	Dimensions					
Ref.		Millimeter	s	Inches		
	Min.	Тур.	Max.	Min.	Тур.	Max.
Α	2.10		2.50	0.083		0.098
A2	0		0.10	0		0.004
В	0.66		0.86	0.026		0.034
B2	5.18		5.48	0.202		0.216
С	0.40		0.60	0.016		0.024
C2	0.44		0.58	0.017		0.023
D	5.90		6.30	0.232		0.248
D1	5.30REF			0.209REF		
E	6.40		6.80	0.252		0.268
E1	4.63			0.182		
G	4.47		4.67	0.176		0.184
Н	9.50		10.70	0.374		0.421
L	1.09		1.21	0.043		0.048
L2	1.35		1.65	0.053		0.065
V1		7°			7°	
V2	0°		6°	0°		6°

Reel Spectification-TO252-3L



	Dimensions						
Ref.		Millimete	ers	Inches			
	Min.	Тур.	Max.	Min.	Тур.	Max.	
W	15.90	16.00	16.10	0.626	0.630	0.634	
E	1.65	1.75	1.85	0.065	0.069	0.073	
F	7.40	7.50	7.60	0.291	0.295	0.299	
D0	1.40	1.50	1.60	0.055	0.059	0.063	
D1	1.40	1.50	1.60	0.055	0.059	0.063	
P0	3.90	4.00	4.10	0.154	0.157	0.161	
P1	7.90	8.00	8.10	0.311	0.315	0.319	
P2	1.90	2.00	2.10	0.075	0.079	0.083	
A0	6.85	6.90	7.00	0.270	0.271	0.276	
В0	10.45	10.50	10.60	0.411	0.413	0.417	
K0	2.68	2.78	2.88	0.105	0.109	0.113	
Т	0.24		0.27	0.009		0.011	
t1	0.10			0.004			
10P0	39.80	40.00	40.20	1.567	1.575	1.583	